

## GE04N70B

### N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	650/700V
RDS(ON)	2.4Ω
ID	4A

### Description

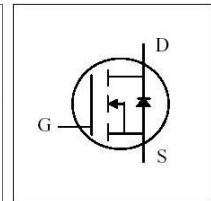
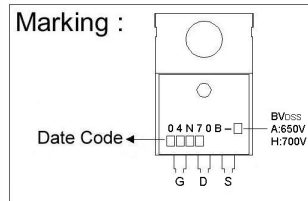
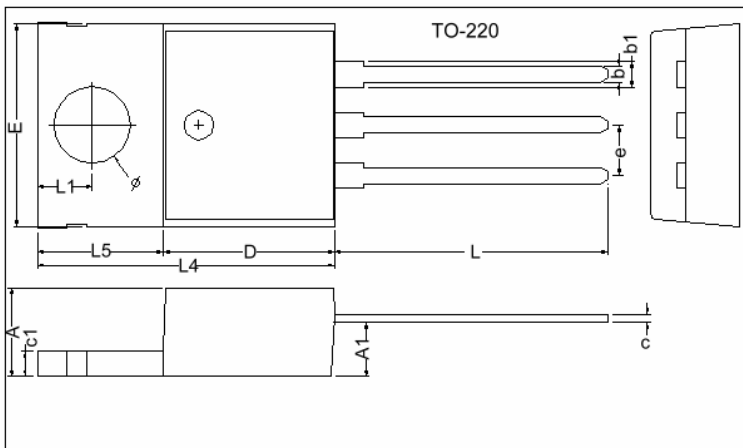
The GE04N70B series are specially designed as main switching devices for universal 90~265VAC off-line AC/DC converter applications. TO-220 type provide high blocking voltage to overcome voltage surge and sag in the toughest power system with the best combination of fast switching, ruggedized design and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications. The device is suited for switch mode power supplies, DC-AC converters and high current high speed switching circuits.

### Features

- \*Simple Drive Requirement
- \*Dynamic dv/dt Rating
- \*Repetitive Avalanche Rated
- \*Fast Switching

### Package Dimensions



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	4.40	4.80	c1	1.25	1.45
b	0.76	1.00	b1	1.17	1.47
c	0.36	0.50	L	13.25	14.25
D	8.60	9.00	e	2.54 REF.	
E	9.80	10.4	L1	2.60	2.89
L4	14.7	15.3	∅	3.71	3.96
L5	6.20	6.60	A1	2.60	2.80

### Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	A/H $V_{DS}$	650/700	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_C=25^{\circ}C$	4	A
Continuous Drain Current, $V_{GS}@10V$	$I_D @T_C=100^{\circ}C$	2.5	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	15	A
Total Power Dissipation	$P_D @T_C=25^{\circ}C$	62.5	W
Linear Derating Factor		0.5	W/°C
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	100	mJ
Avalanche Current	$I_{AR}$	4	A
Repetitive Avalanche Energy	$E_{AR}$	4	mJ
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150	°C

### Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-case	Max. $R_{thj-c}$	2.0	°C/W
Thermal Resistance Junction-ambient	Max. $R_{thj-a}$	62	°C/W

**Electrical Characteristics(T<sub>j</sub> = 25°C Unless otherwise specified)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	650	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> =250uA A
		700	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> =250uA H
Breakdown Voltage Temperature Coefficient	ΔBV <sub>DSS</sub> /ΔT <sub>j</sub>	-	0.6	-	V/°C	Reference to 25°C, I <sub>D</sub> =1mA
Gate Threshold Voltage	V <sub>GS(th)</sub>	2.0	-	4.0	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA
Forward Transconductance	g <sub>fs</sub>	-	2.5	-	S	V <sub>DS</sub> =50V, I <sub>D</sub> =2A
Gate-Source Leakage Current	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> = ±20V
Drain-Source Leakage Current(T <sub>j</sub> =25°C)	I <sub>DSS</sub>	-	-	100	uA	V <sub>DS</sub> =600V, V <sub>GS</sub> =0
Drain-Source Leakage Current(T <sub>j</sub> =150°C)		-	-	500	uA	V <sub>DS</sub> =480V, V <sub>GS</sub> =0
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	-	2.4	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =2A
Total Gate Charge <sup>3</sup>	Q <sub>g</sub>	-	16.7	-	nC	I <sub>D</sub> =4A V <sub>DS</sub> =480V V <sub>GS</sub> =10V
Gate-Source Charge	Q <sub>gs</sub>	-	4.1	-		
Gate-Drain ("Miller") Change	Q <sub>gd</sub>	-	4.9	-		
Turn-on Delay Time <sup>3</sup>	T <sub>d(on)</sub>	-	11	-	ns	V <sub>DD</sub> =300V I <sub>D</sub> =4A V <sub>GS</sub> =10V R <sub>G</sub> =10Ω R <sub>D</sub> =75Ω
Rise Time	T <sub>r</sub>	-	8.3	-		
Turn-off Delay Time	T <sub>d(off)</sub>	-	23.8	-		
Fall Time	T <sub>f</sub>	-	8.2	-		
Input Capacitance	C <sub>iss</sub>	-	950	-	pF	V <sub>GS</sub> =0V V <sub>DS</sub> =25V f=1.0MHz
Output Capacitance	C <sub>oss</sub>	-	65	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	6	-		

**Source-Drain Diode**

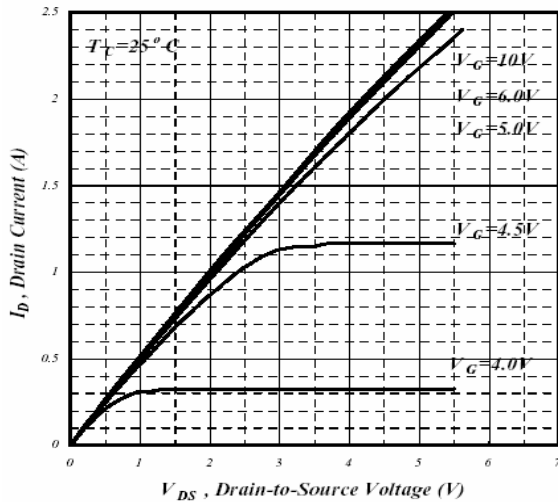
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage <sup>3</sup>	V <sub>SD</sub>	-	-	1.5	V	I <sub>S</sub> =4A, V <sub>GS</sub> =0V, T <sub>j</sub> =25°C
Continuous Source Current(Body Diode)	I <sub>S</sub>	-	-	4	A	V <sub>D</sub> = V <sub>G</sub> =0V, V <sub>S</sub> =1.5V
Pulsed Source Current (Body Diode) <sup>1</sup>	I <sub>SM</sub>	-	-	15	A	

Notes: 1. Pulse width limited by safe operating area.

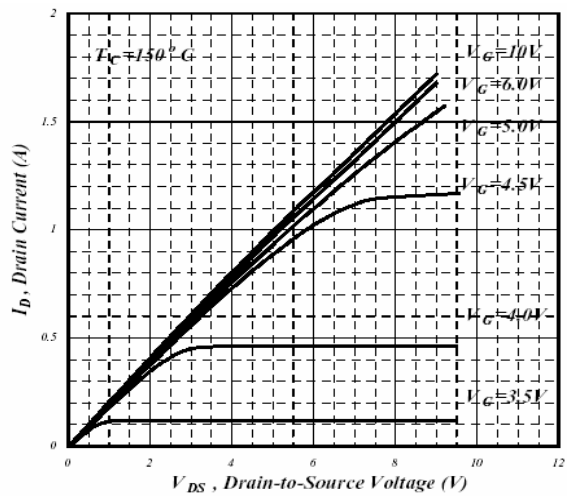
2. Staring T<sub>j</sub>=25°C, V<sub>DD</sub>=50V, L=25mH, R<sub>G</sub>=25Ω, I<sub>AS</sub>=4A.

3. Pulse width ≤ 300us, duty cycle ≤ 2%.

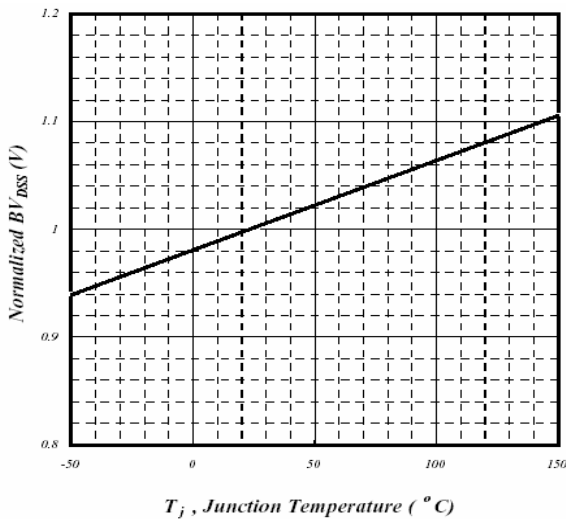
## Characteristics Curve



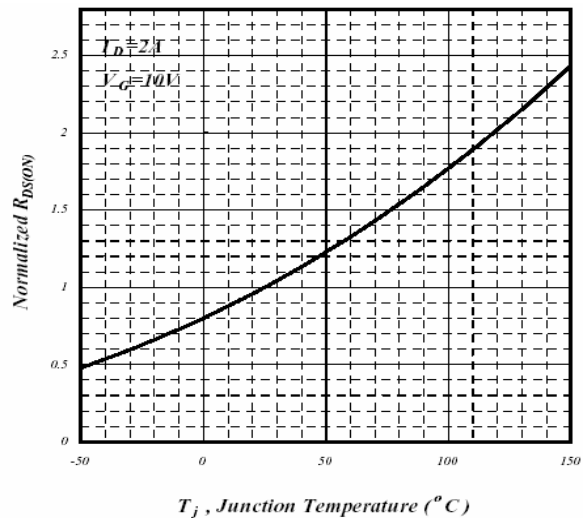
**Fig 1. Typical Output Characteristics**



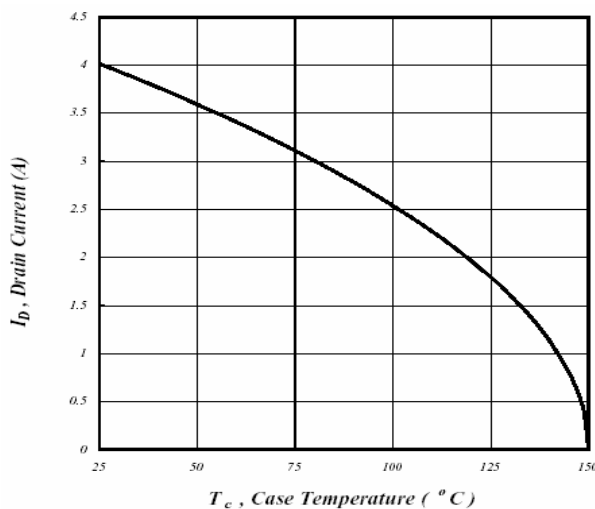
**Fig 2. Typical Output Characteristics**



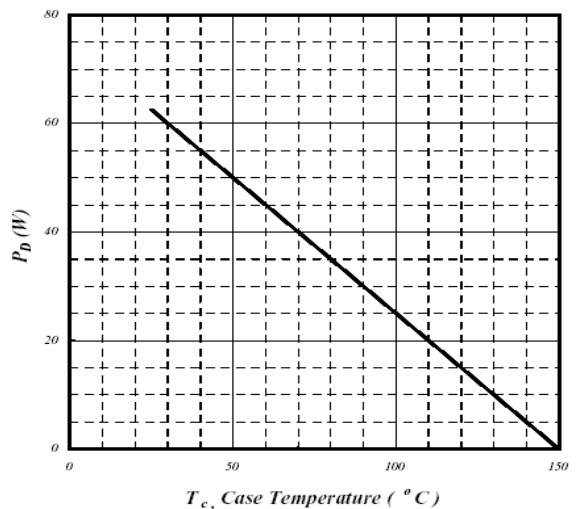
**Fig 3. Normalized  $BV_{DSS}$  v.s. Junction Temperature**



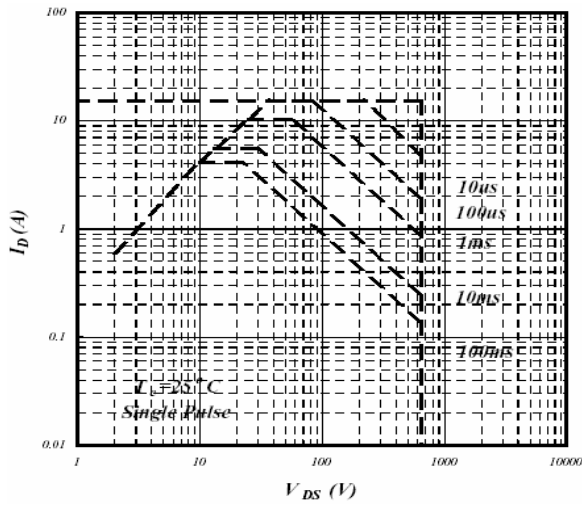
**Fig 4. Normalized On-Resistance v.s. Junction Temperature**



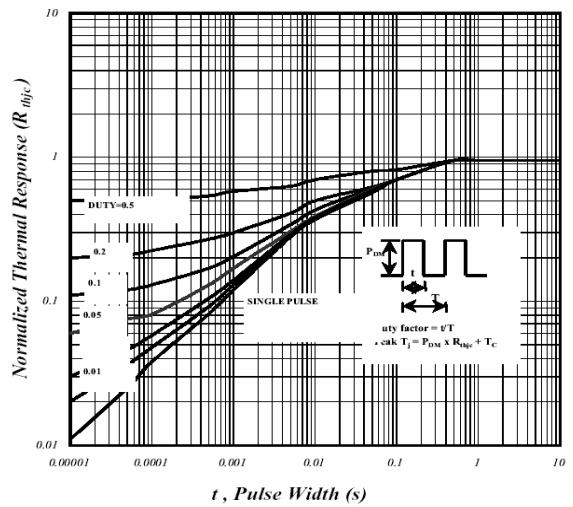
**Fig 5. Maximum Drain Current v.s. Case Temperature**



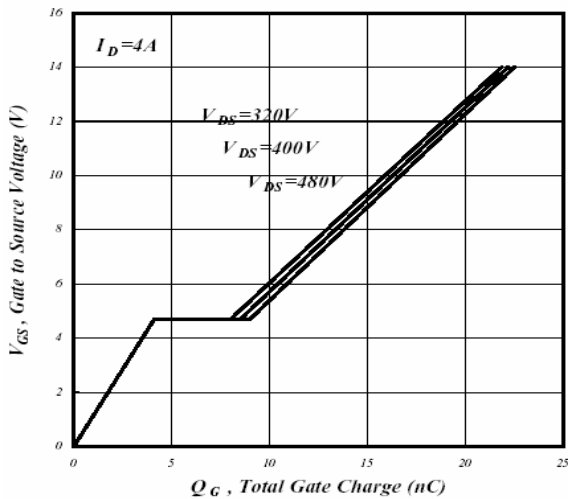
**Fig 6. Typical Power Dissipation**



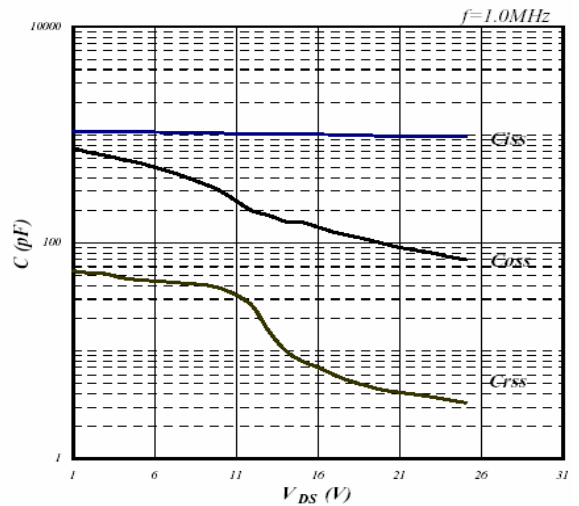
**Fig 7. Maximum Safe Operating Area**



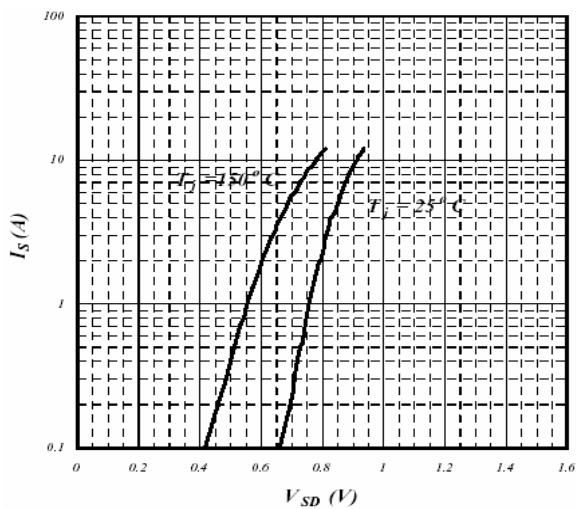
**Fig 8. Effective Transient Thermal Impedance**



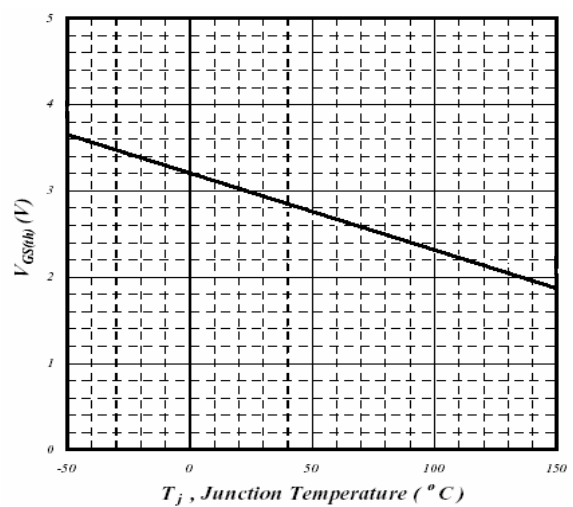
**Fig 9. Gate Charge Characteristics**



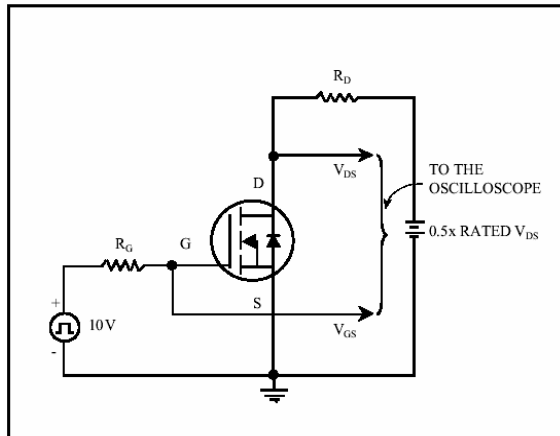
**Fig 10. Typical Capacitance Characteristics**



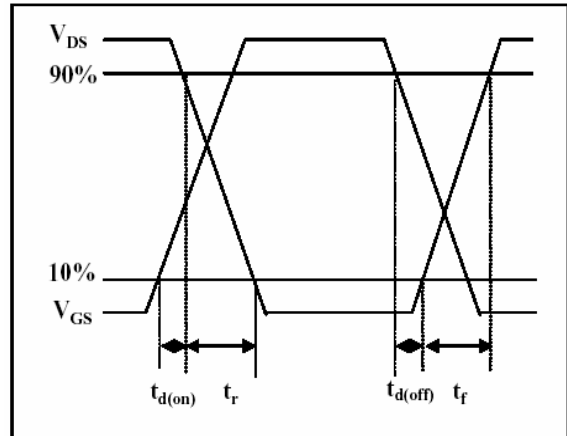
**Fig 11. Forward Characteristics of Reverse Diode**



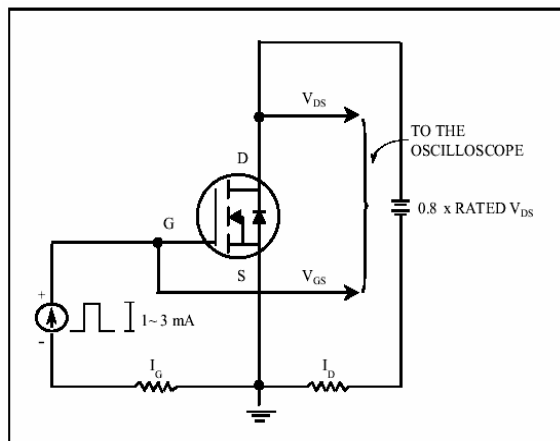
**Fig 12. Gate Threshold Voltage v.s. Junction Temperature**



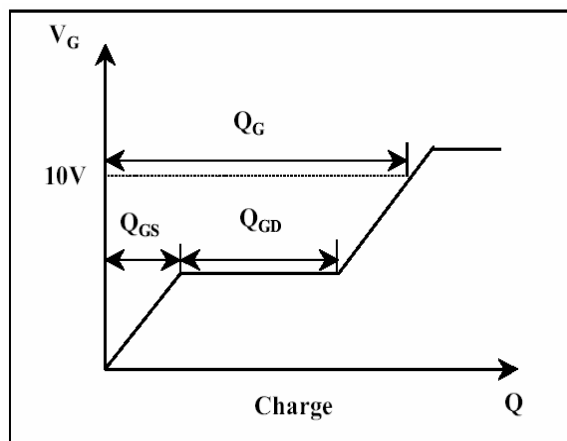
**Fig 13. Switching Time Circuit**



**Fig 14. Switching Time Waveform**



**Fig 15. Gate Charge Circuit**



**Fig 16. Gate Charge Waveform**

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